

SILICON EPITAXIAL TRANSISTOR

P-N-P transistor in a microminiature (SMD) plastic package intended for surface mounted applications. The PMBT3906 is primarily intended for use in telephony and professional communication equipment.

QUICK REFERENCE DATA

Collector-base voltage (open emitter)	$-V_{CBO}$	max.	40 V
Collector-emitter voltage (open base)	$-V_{CEO}$	max.	40 V
Emitter-base voltage (open collector)	$-V_{EBO}$	max.	5 V
Collector current (d.c.)	$-I_C$	max.	200 mA
Total power dissipation up to $T_{amb} = 25\text{ }^\circ\text{C}$	P_{tot}	max.	250 mW
D.C. current gain	h_{FE}		100 to 300
Transition frequency at $f = 100\text{ MHz}$	f_T	min.	250 MHz
$-I_C = 10\text{ mA}; -V_{CE} = 1\text{ V}$			
$-I_C = 10\text{ mA}; -V_{CE} = 20\text{ V}$			

MECHANICAL DATA

Dimensions in mm

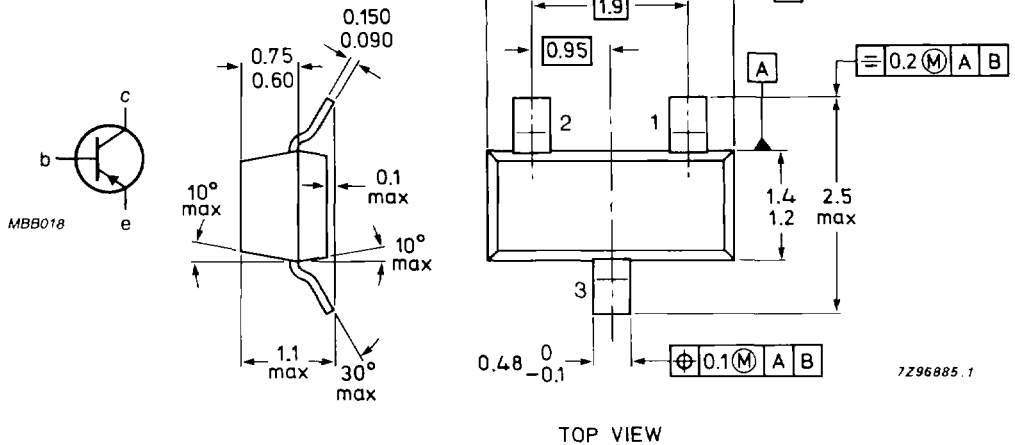
Fig. 1 SOT-23.

Pinning:

- 1 = base
- 2 = emitter
- 3 = collector

Marking code

PMBT3906 : p2A



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage (open emitter)	$-V_{CBO}$	max.	40 V
Collector-emitter voltage (open base)	$-V_{CEO}$	max.	40 V
Emitter-base voltage (open collector)	$-V_{EBO}$	max.	5 V
Collector current (d.c.)	$-I_C$	max.	200 mA
Total power dissipation* up to $T_{amb} = 25\text{ }^\circ\text{C}$	P_{tot}	max.	250 mW
Storage temperature	T_{stg}		-65 to +150 $^\circ\text{C}$

THERMAL CHARACTERISTICS

$$T_j = P(R_{th\ j-t} + R_{th\ t-s} + R_{th\ s-a}) + T_{amb}$$

Thermal resistance

from junction to ambient $R_{th\ j-a} = 500\text{ K/W}$

CHARACTERISTICS

$T_{amb} = 25\text{ }^\circ\text{C}$ unless otherwise specified

Collector-emitter breakdown voltage▲ $-I_C = 1\text{ mA}; I_E = 0$	$-V_{(BR)CEO}$	min.	40 V
Collector-base breakdown voltage $-I_C = 10\text{ }\mu\text{A}; I_E = 0$	$-V_{(BR)CBO}$	min.	40 V
Emitter-base breakdown voltage $-I_E = 10\text{ }\mu\text{A}; I_C = 0$	$-V_{(BR)EBO}$	min.	5 V
Collector cut-off current $-V_{CE} = 30\text{ V}; -V_{EB} = 3\text{ V}$	$-I_{CE}$	max.	50 nA
Base current with reverse biased emitter junction	$-I_{BEX}$	max.	50 nA
Output capacitance at $f = 100\text{ kHz}$ $I_E = 0; -V_{CB} = 5\text{ V}$	C_c	max.	4,5 pF
Input capacitance at $f = 100\text{ kHz}$ $I_C = 0; -V_{BE} = 0,5\text{ V}$	C_e	max.	10 pF

* Mounted on an FR4 printed-circuit board 8 mm x 10 mm x 0.7 mm.

▲ Pulse test conditions: $t_p = 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

Saturation voltages

 $-I_C = 10 \text{ mA}; -I_B = 1 \text{ mA}$ $-V_{CEsat}$ max. 0,25 V $-I_C = 50 \text{ mA}; -I_B = 5 \text{ mA}$ $-V_{CEsat}$ max. 0,4 V $-I_C = 10 \text{ mA}; -I_B = 1 \text{ mA}$ $-V_{BEsat}$ min. 0,65 V $-I_C = 50 \text{ mA}; -I_B = 5 \text{ mA}$ $-V_{BEsat}$ max. 0,85 V

D.C. current gain

 $-I_C = 0,1 \text{ mA}; -V_{CE} = 1 \text{ V}$ $-V_{BBsat}$ max. 0,95 V $-I_C = 1 \text{ mA}; -V_{CE} = 1 \text{ V}$ h_{FE} min. 60 $-I_C = 10 \text{ mA}; -V_{CE} = 1 \text{ V}$ h_{FE} min. 80 $-I_C = 50 \text{ mA}; -V_{CE} = 1 \text{ V}$ h_{FE} min. 100 $-I_C = 100 \text{ mA}; -V_{CE} = 1 \text{ V}$ h_{FE} max. 300Transition frequency at $f = 100 \text{ MHz}$ $-I_C = 10 \text{ mA}; -V_{CE} = 20 \text{ V}$ h_{FE} min. 60Noise figure at $R_S = 1 \text{ k}\Omega$ $-I_C = 100 \mu\text{A}; -V_{CE} = 5 \text{ V}$ h_{FE} min. 80 $f = 10 \text{ Hz to } 15,7 \text{ kHz}$ h_{FE} min. 100

Switching times

Turn-on time when $-V_{CC} = 3 \text{ V}; -V_{BE} = 0,5 \text{ V}$ $-I_C = 10 \text{ mA}; -I_{Bon} = 1 \text{ mA}$ h_{FE} max. 300

Delay time

 f_T min. 250 MHz

Rise time

Turn-off time when $-V_{CC} = 3 \text{ V}; -I_C = 10 \text{ mA}$ $-I_{Bon} = -I_{Boff} = 1 \text{ mA}$

F max. 4 dB

Storage time

 t_d max. 35 ns

Fall time

 t_r max. 35 ns t_s max. 225 ns t_f max. 75 ns